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# XMC1300 AB-Step

Microcontroller Series  
for Industrial Applications

XMC1000 Family

ARM<sup>®</sup> Cortex<sup>®</sup>-M0  
32-bit processor core

Data Sheet

V1.9 2017-03

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## **XMC1300 Data Sheet**

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### **Revision History: V1.9 2017-03**

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Previous Version: V1.8 2016-09

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Page	Subjects
<b>Page 10,</b> <b>Page 12</b>	Add marking option for XMC1301-T038X0032.

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## **About this Document**

This Data Sheet is addressed to embedded hardware and software developers. It provides the reader with detailed descriptions about the ordering designations, available features, electrical and physical characteristics of the XMC1300 series devices.

The document describes the characteristics of a superset of the XMC1300 series devices. For simplicity, the various device types are referred to by the collective term XMC1300 throughout this document.

### **XMC1000 Family User Documentation**

The set of user documentation includes:

- **Reference Manual**
  - describes the functionality of the superset of devices.
- **Data Sheets**
  - list the complete ordering designations, available features and electrical characteristics of derivative devices.
- **Errata Sheets**
  - list deviations from the specifications given in the related Reference Manual or Data Sheets. Errata Sheets are provided for the superset of devices.

***Attention: Please consult all parts of the documentation set to attain consolidated knowledge about your device.***

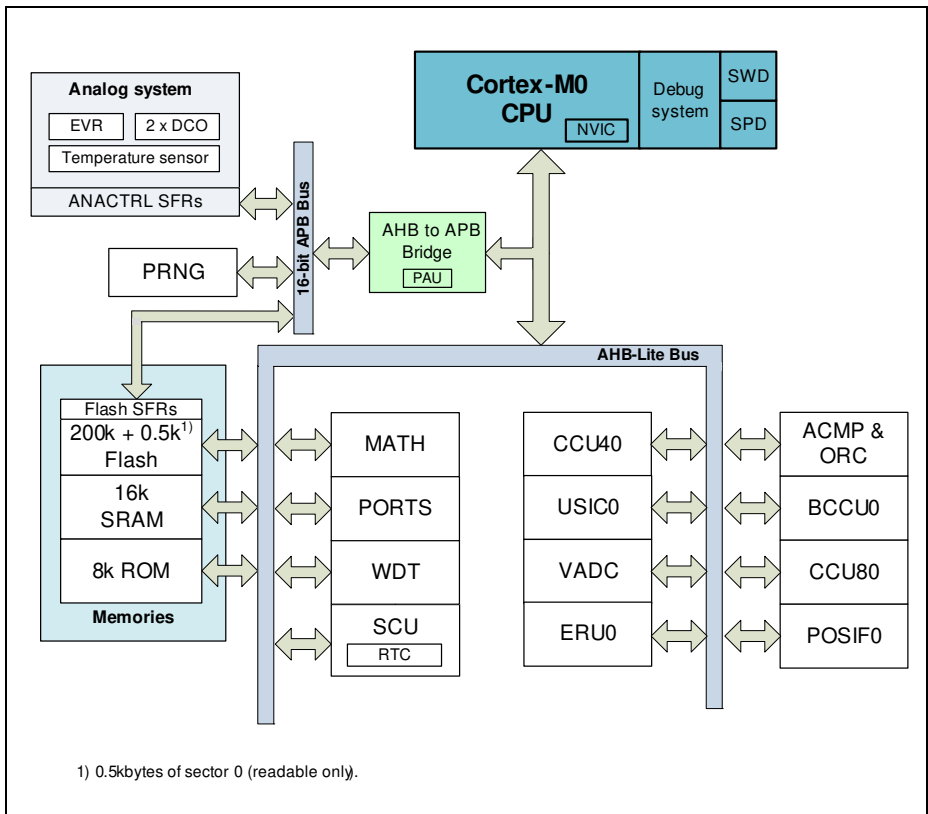
Application related guidance is provided by **Users Guides** and **Application Notes**.

Please refer to <http://www.infineon.com/xmc1000> to get access to the latest versions of those documents.



# 1 Summary of Features

The XMC1300 devices are members of the XMC1000 Family of microcontrollers based on the ARM Cortex-M0 processor core. The XMC1300 series addresses the real-time control needs of motor control, digital power conversion. It also features peripherals for LED Lighting applications.



**Figure 1 System Block Diagram**

## CPU Subsystem

- CPU Core
  - High-performance 32-bit ARM Cortex-M0 CPU
  - Most 16-bit Thumb and subset of 32-bit Thumb2 instruction set
  - Single cycle 32-bit hardware multiplier
  - System timer (SysTick) for Operating System support

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## Summary of Features

- Ultra low power consumption
- Nested Vectored Interrupt Controller (NVIC)
- Event Request Unit (ERU) for processing of external and internal service requests
- MATH Co-processor (MATH)
  - CORDIC unit for trigonometric calculation
  - division unit

### On-Chip Memories

- 8 kbytes on-chip ROM
- 16 kbytes on-chip high-speed SRAM
- up to 200 kbytes on-chip Flash program and data memory

### Communication Peripherals

- Two Universal Serial Interface Channels (USIC), usable as UART, double-SPI, quad-SPI, IIC, IIS and LIN interfaces

### Analog Frontend Peripherals

- A/D Converters
  - up to 12 analog input pins
  - 2 sample and hold stages with 8 analog input channels each
  - fast 12-bit analog to digital converter with adjustable gain
- Up to 8 channels of out of range comparators (ORC)
- Up to 3 fast analog comparators (ACMP)
- Temperature Sensor (TSE)

### Industrial Control Peripherals

- Capture/Compare Units 4 (CCU4) as general purpose timers
- Capture/Compare Units 8 (CCU8) for motor control and power conversion
- Position Interfaces (POSIF) for hall and quadrature encoders and motor positioning
- Brightness and Colour Control Unit (BCCU), for LED color and dimming application

### System Control

- Window Watchdog Timer (WDT) for safety sensitive applications
- Real Time Clock module with alarm support (RTC)
- System Control Unit (SCU) for system configuration and control
- Pseudo random number generator (PRNG) for fast random data generation

### Input/Output Lines

- Tri-stated in input mode
- Push/pull or open drain output mode

- Configurable pad hysteresis

### **On-Chip Debug Support**

- Support for debug features: 4 breakpoints, 2 watchpoints
- Various interfaces: ARM serial wire debug (SWD), single pin debug (SPD)

## **1.1 Ordering Information**

The ordering code for an Infineon microcontroller provides an exact reference to a specific product. The code “XMC1<DDD>-<Z><PPP><T><FFFF>” identifies:

- <DDD> the derivatives function set
- <Z> the package variant
  - T: TSSOP
  - Q: VQFN
- <PPP> package pin count
- <T> the temperature range:
  - F: -40°C to 85°C
  - X: -40°C to 105°C
- <FFFF> the Flash memory size.

For ordering codes for the XMC1300 please contact your sales representative or local distributor.

This document describes several derivatives of the XMC1300 series, some descriptions may not apply to a specific product. Please see [Table 1](#).

For simplicity the term **XMC1300** is used for all derivatives throughout this document.

## **1.2 Device Types**

These device types are available and can be ordered through Infineon’s direct and/or distribution channels.

**Table 1 Synopsis of XMC1300 Device Types**

<b>Derivative</b>	<b>Package</b>	<b>Flash Kbytes</b>	<b>SRAM Kbytes</b>
XMC1301-T016F0008	PG-TSSOP-16-8	8	16
XMC1301-T016F0016	PG-TSSOP-16-8	16	16
XMC1301-T016F0032	PG-TSSOP-16-8	32	16
XMC1301-T016X0008	PG-TSSOP-16-8	8	16
XMC1301-T016X0016	PG-TSSOP-16-8	16	16
XMC1302-T016X0008	PG-TSSOP-16-8	8	16

**Summary of Features**
**Table 1 Synopsis of XMC1300 Device Types (cont'd)**

<b>Derivative</b>	<b>Package</b>	<b>Flash Kbytes</b>	<b>SRAM Kbytes</b>
XMC1302-T016X0016	PG-TSSOP-16-8	16	16
XMC1302-T016X0032	PG-TSSOP-16-8	32	16
XMC1302-T028X0016	PG-TSSOP-28-8	16	16
XMC1301-T038F0008	PG-TSSOP-38-9	8	16
XMC1301-T038F0016	PG-TSSOP-38-9	16	16
XMC1301-T038F0032	PG-TSSOP-38-9	32	16
XMC1301-T038X0032	PG-TSSOP-38-9	32	16
XMC1301-T038F0064	PG-TSSOP-38-9	64	16
XMC1302-T038X0016	PG-TSSOP-38-9	16	16
XMC1302-T038X0032	PG-TSSOP-38-9	32	16
XMC1302-T038X0064	PG-TSSOP-38-9	64	16
XMC1302-T038X0128	PG-TSSOP-38-9	128	16
XMC1302-T038X0200	PG-TSSOP-38-9	200	16
XMC1301-Q024F0008	PG-VQFN-24-19	8	16
XMC1301-Q024F0016	PG-VQFN-24-19	16	16
XMC1302-Q024F0016	PG-VQFN-24-19	16	16
XMC1302-Q024F0032	PG-VQFN-24-19	32	16
XMC1302-Q024F0064	PG-VQFN-24-19	64	16
XMC1302-Q024X0016	PG-VQFN-24-19	16	16
XMC1302-Q024X0032	PG-VQFN-24-19	32	16
XMC1302-Q024X0064	PG-VQFN-24-19	64	16
XMC1301-Q040F0008	PG-VQFN-40-13	8	16
XMC1301-Q040F0016	PG-VQFN-40-13	16	16
XMC1301-Q040F0032	PG-VQFN-40-13	32	16
XMC1302-Q040X0016	PG-VQFN-40-13	16	16
XMC1302-Q040X0032	PG-VQFN-40-13	32	16
XMC1302-Q040X0064	PG-VQFN-40-13	64	16
XMC1302-Q040X0128	PG-VQFN-40-13	128	16
XMC1302-Q040X0200	PG-VQFN-40-13	200	16

### 1.3 Device Type Features

The following table lists the available features per device type.

**Table 2 Features of XMC1300 Device Types<sup>1)</sup>**

Derivative	ADC channel	ACMP	BCCU	MATH
XMC1301-T016	11	2	-	-
XMC1302-T016	11	2	1	1
XMC1302-T028	14	3	1	1
XMC1301-T038	16	3	-	-
XMC1302-T038	16	3	1	1
XMC1301-Q024	13	3	-	-
XMC1302-Q024	13	3	1	1
XMC1301-Q040	16	3	-	-
XMC1302-Q040	16	3	1	1

1) Features that are not included in this table are available in all the derivatives

**Table 3 ADC Channels<sup>1)</sup>**

Package	VADC0 G0	VADC0 G1
PG-TSSOP-16	CH0..CH5	CH0..CH4
PG-TSSOP-28	CH0..CH7	CH0 .. CH4, CH7
PG-TSSOP-38	CH0..CH7	CH0..CH7
PG-VQFN-24	CH0..CH7	CH0..CH4
PG-VQFN-40	CH0..CH7	CH0..CH7

1) Some pins in a package may be connected to more than one channel. For the detailed mapping see the Port I/O Function table.

### 1.4 Chip Identification Number

The Chip Identification Number allows software to identify the marking. It is a 8 words value with the most significant 7 words stored in Flash configuration sector 0 (CS0) at address location : 1000 0F00<sub>H</sub> (MSB) - 1000 0F1B<sub>H</sub> (LSB). The least significant word and most significant word of the Chip Identification Number are the value of registers DBGROMID and IDCHIP, respectively.

**Table 4 XMC1300 Chip Identification Number**

<b>Derivative</b>	<b>Value</b>	<b>Marking</b>
XMC1301-T016F0008	00013032 01CF00FF 00001FF7 0000100F 00000C00 00001000 00003000 201ED083 <sub>H</sub>	AB
XMC1301-T016F0016	00013032 01CF00FF 00001FF7 0000100F 00000C00 00001000 00005000 201ED083 <sub>H</sub>	AB
XMC1301-T016F0032	00013032 01CF00FF 00001FF7 0000100F 00000C00 00001000 00009000 201ED083 <sub>H</sub>	AB
XMC1301-T016X0008	00013033 01CF00FF 00001FF7 0000100F 00000C00 00001000 00003000 201ED083 <sub>H</sub>	AB
XMC1301-T016X0016	00013033 01CF00FF 00001FF7 0000100F 00000C00 00001000 00005000 201ED083 <sub>H</sub>	AB
XMC1302-T016X0008	00013033 01FF00FF 00001FF7 0000900F 00000C00 00001000 00003000 201ED083 <sub>H</sub>	AB
XMC1302-T016X0016	00013033 01FF00FF 00001FF7 0000900F 00000C00 00001000 00005000 201ED083 <sub>H</sub>	AB
XMC1302-T016X0032	00013033 01FF00FF 00001FF7 0000900F 00000C00 00001000 00009000 201ED083 <sub>H</sub>	AB
XMC1302-T028X0016	00013023 01FF00FF 00001FF7 0000900F 00000C00 00001000 00005000 201ED083 <sub>H</sub>	AB
XMC1301-T038F0008	00013012 01CF00FF 00001FF7 0000100F 00000C00 00001000 00003000 201ED083 <sub>H</sub>	AB
XMC1301-T038F0016	00013012 01CF00FF 00001FF7 0000100F 00000C00 00001000 00005000 201ED083 <sub>H</sub>	AB
XMC1301-T038F0032	00013012 01CF00FF 00001FF7 0000100F 00000C00 00001000 00009000 201ED083 <sub>H</sub>	AB
XMC1301-T038X0032	00013013 01CF00FF 00001FF7 0000100F 00000C00 00001000 00009000 201ED083 <sub>H</sub>	AB
XMC1301-T038F0064	00013012 01CF00FF 00001FF7 0000100F 00000C00 00001000 00011000 201ED083 <sub>H</sub>	AB
XMC1302-T038X0016	00013013 01FF00FF 00001FF7 0000900F 00000C00 00001000 00005000 201ED083 <sub>H</sub>	AB
XMC1302-T038X0032	00013013 01FF00FF 00001FF7 0000900F 00000C00 00001000 00009000 201ED083 <sub>H</sub>	AB
XMC1302-T038X0064	00013013 01FF00FF 00001FF7 0000900F 00000C00 00001000 00011000 201ED083 <sub>H</sub>	AB

**Summary of Features**

**Table 4 XMC1300 Chip Identification Number (cont'd)**

<b>Derivative</b>	<b>Value</b>	<b>Marking</b>
XMC1302-T038X0128	00013013 01FF00FF 00001FF7 0000900F 00000C00 00001000 00021000 201ED083 <sub>H</sub>	AB
XMC1302-T038X0200	00013013 01FF00FF 00001FF7 0000900F 00000C00 00001000 00033000 201ED083 <sub>H</sub>	AB
XMC1301-Q024F0008	00013062 01CF00FF 00001FF7 0000100F 00000C00 00001000 00003000 201ED083 <sub>H</sub>	AB
XMC1301-Q024F0016	00013062 01CF00FF 00001FF7 0000100F 00000C00 00001000 00005000 201ED083 <sub>H</sub>	AB
XMC1302-Q024F0016	00013062 01FF00FF 00001FF7 0000900F 00000C00 00001000 00005000 201ED083 <sub>H</sub>	AB
XMC1302-Q024F0032	00013062 01FF00FF 00001FF7 0000900F 00000C00 00001000 00009000 201ED083 <sub>H</sub>	AB
XMC1302-Q024F0064	00013062 01FF00FF 00001FF7 0000900F 00000C00 00001000 00011000 201ED083 <sub>H</sub>	AB
XMC1302-Q024X0016	00013063 01FF00FF 00001FF7 0000900F 00000C00 00001000 00005000 201ED083 <sub>H</sub>	AB
XMC1302-Q024X0032	00013063 01FF00FF 00001FF7 0000900F 00000C00 00001000 00009000 201ED083 <sub>H</sub>	AB
XMC1302-Q024X0064	00013063 01FF00FF 00001FF7 0000900F 00000C00 00001000 00011000 201ED083 <sub>H</sub>	AB
XMC1301-Q040F0008	00013042 01CF00FF 00001FF7 0000100F 00000C00 00001000 00003000 201ED083 <sub>H</sub>	AB
XMC1301-Q040F0016	00013042 01CF00FF 00001FF7 0000100F 00000C00 00001000 00005000 201ED083 <sub>H</sub>	AB
XMC1301-Q040F0032	00013042 01CF00FF 00001FF7 0000100F 00000C00 00001000 00009000 201ED083 <sub>H</sub>	AB
XMC1302-Q040X0016	00013043 01FF00FF 00001FF7 0000900F 00000C00 00001000 00005000 201ED083 <sub>H</sub>	AB
XMC1302-Q040X0032	00013043 01FF00FF 00001FF7 0000900F 00000C00 00001000 00009000 201ED083 <sub>H</sub>	AB
XMC1302-Q040X0064	00013043 01FF00FF 00001FF7 0000900F 00000C00 00001000 00011000 201ED083 <sub>H</sub>	AB

**Summary of Features**

**Table 4 XMC1300 Chip Identification Number (cont'd)**

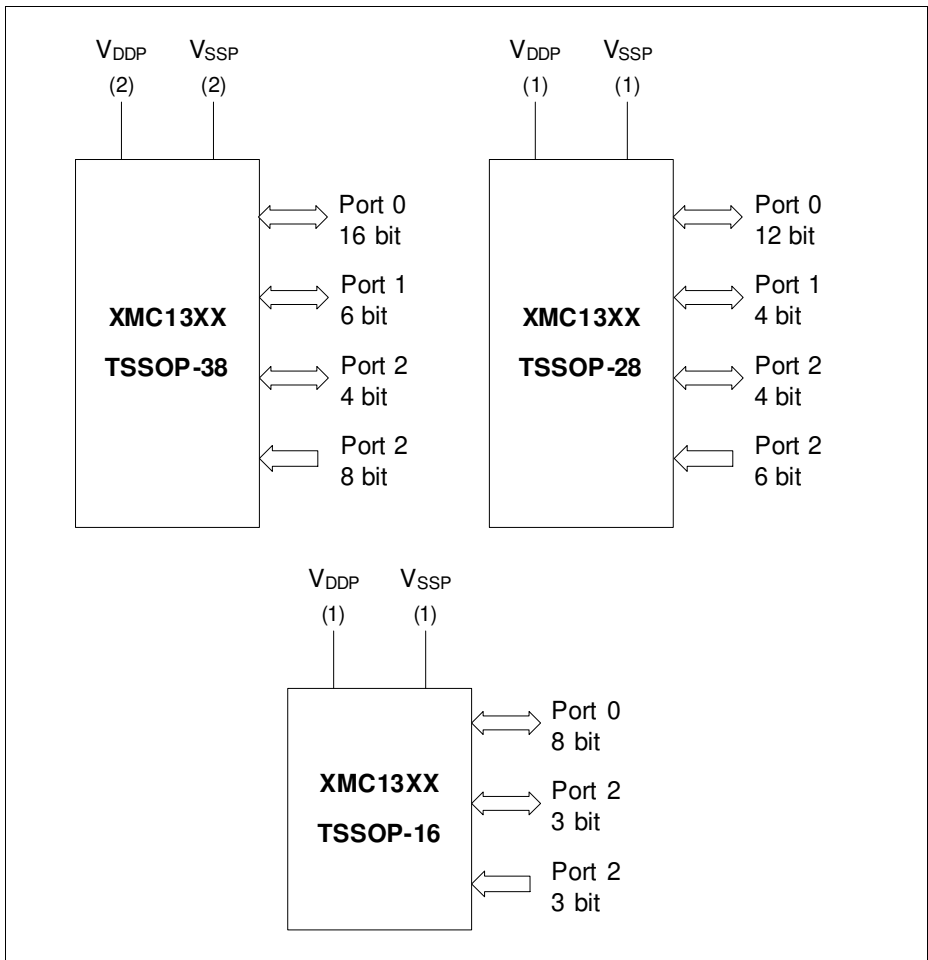
<b>Derivative</b>	<b>Value</b>	<b>Marking</b>
XMC1302-Q040X0128	00013043 01FF00FF 00001FF7 0000900F 00000C00 00001000 00021000 201ED083 <sub>H</sub>	AB
XMC1302-Q040X0200	00013043 01FF00FF 00001FF7 0000900F 00000C00 00001000 00033000 201ED083 <sub>H</sub>	AB



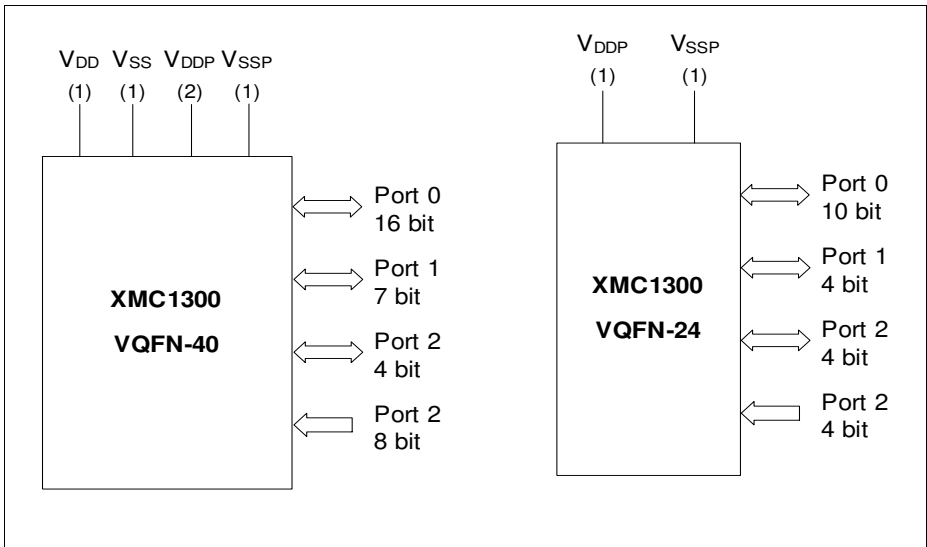
## 2 General Device Information

This section summarizes the logic symbols and package pin configurations with a detailed list of the functional I/O mapping.

### 2.1 Logic Symbols



**Figure 2 XMC1300 Logic Symbol for TSSOP-38, TSSOP-28 and TSSOP-16**



**Figure 3 XMC1300 Logic Symbol for VQFN-24 and VQFN-40**

## 2.2 Pin Configuration and Definition

The following figures summarize all pins, showing their locations on the different packages.

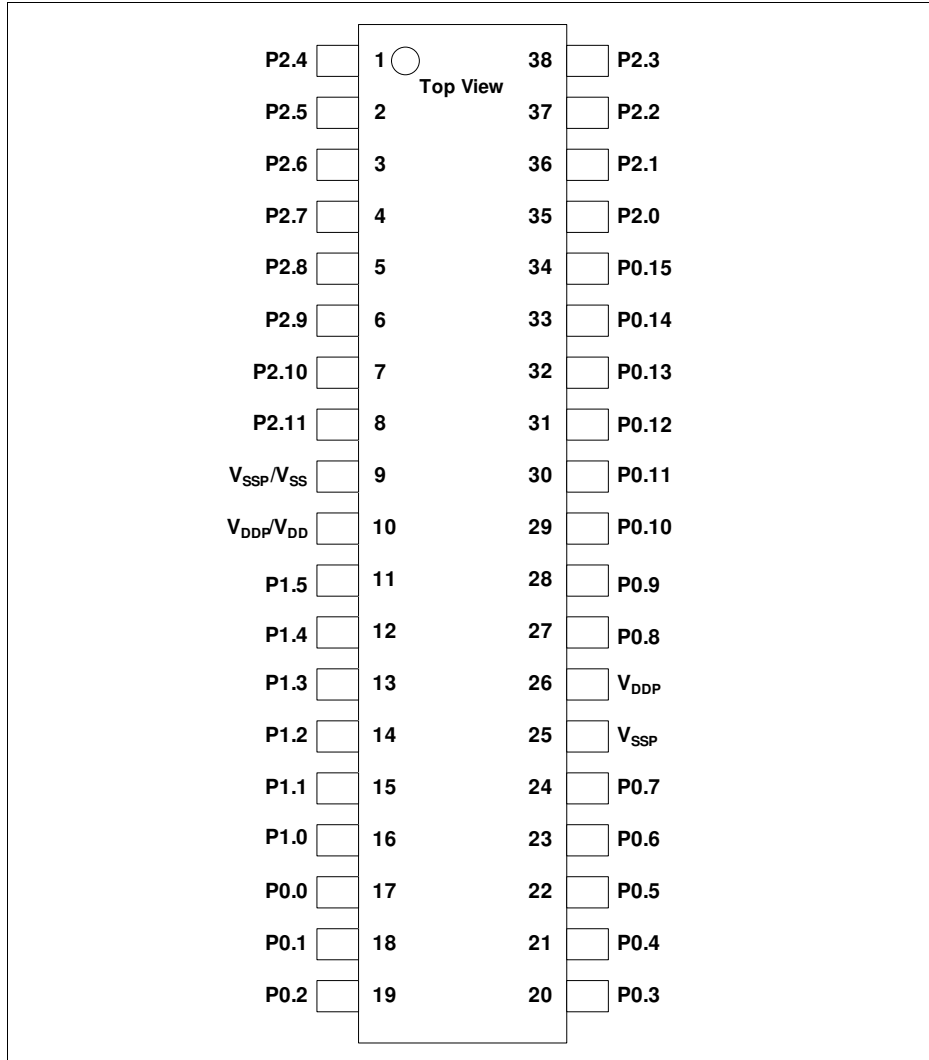
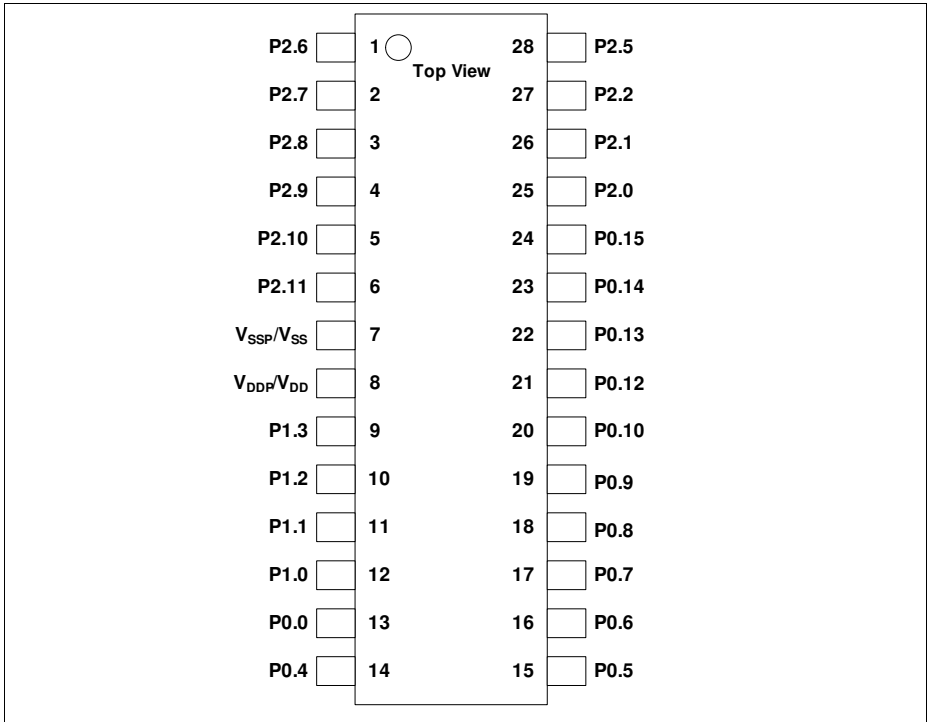
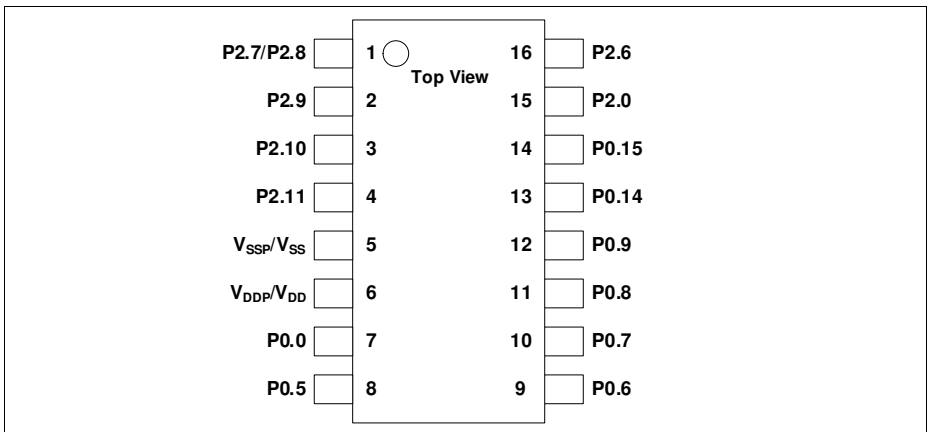


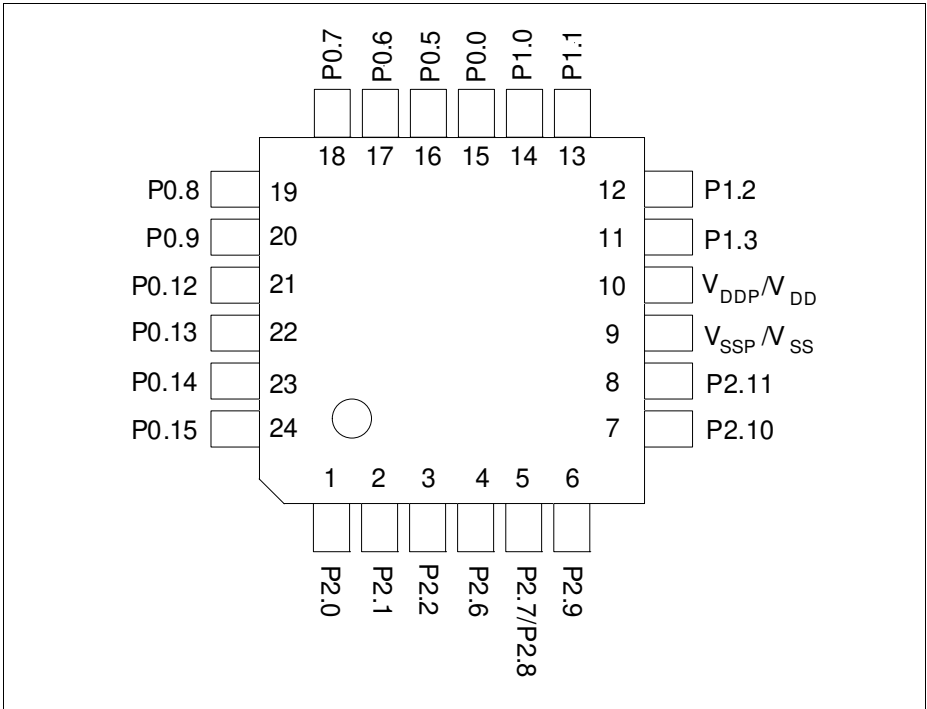
Figure 4 XMC1300 PG-TSSOP-38 Pin Configuration (top view)



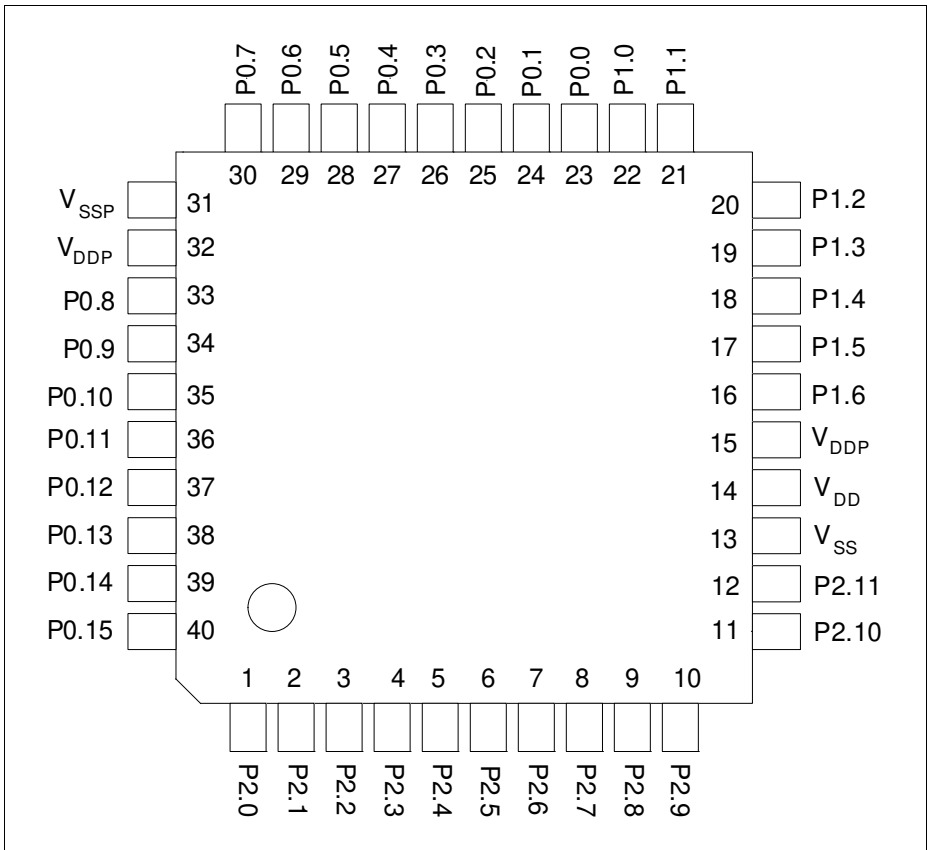
**Figure 5 XMC1300 PG-TSSOP-28 Pin Configuration (top view)**



**Figure 6 XMC1300 PG-TSSOP-16 Pin Configuration (top view)**



**Figure 7 XMC1300 PG-VQFN-24 Pin Configuration (top view)**



**Figure 8 XMC1300 PG-VQFN-40 Pin Configuration (top view)**

### 2.2.1 Package Pin Summary

The following general building block is used to describe each pin:

**Table 5 Package Pin Mapping Description**

Function	Package A	Package B	...	Pad Type
Px.y	N	N		Pad Class

The table is sorted by the “Function” column, starting with the regular Port pins (Px.y), followed by the supply pins.

The following columns, titled with the supported package variants, lists the package pin number to which the respective function is mapped in that package.

The “Pad Type” indicates the employed pad type:

- STD\_INOUT(standard bi-directional pads)
- STD\_INOUT/AN (standard bi-directional pads with analog input)
- High Current (high current bi-directional pads)
- STD\_IN/AN (standard input pads with analog input)
- Power (power supply)

Details about the pad properties are defined in the Electrical Parameters.

**Table 6 Package Pin Mapping**

Function	VQFN 40	TSSOP 38	TSSOP 28	VQFN 24	TSSOP 16	Pad Type	Notes
P0.0	23	17	13	15	7	STD_IN OUT	
P0.1	24	18	-	-	-	STD_IN OUT	
P0.2	25	19	-	-	-	STD_IN OUT	
P0.3	26	20	-	-	-	STD_IN OUT	
P0.4	27	21	14	-	-	STD_IN OUT	
P0.5	28	22	15	16	8	STD_IN OUT	
P0.6	29	23	16	17	9	STD_IN OUT	

**General Device Information**
**Table 6 Package Pin Mapping (cont'd)**

Function	VQFN 40	TSSOP 38	TSSOP 28	VQFN 24	TSSOP 16	Pad Type	Notes
P0.7	30	24	17	18	10	STD_IN OUT	
P0.8	33	27	18	19	11	STD_IN OUT	
P0.9	34	28	19	20	12	STD_IN OUT	
P0.10	35	29	20	-	-	STD_IN OUT	
P0.11	36	30	-	-	-	STD_IN OUT	
P0.12	37	31	21	21	-	STD_IN OUT	
P0.13	38	32	22	22	-	STD_IN OUT	
P0.14	39	33	23	23	13	STD_IN OUT	
P0.15	40	34	24	24	14	STD_IN OUT	
P1.0	22	16	12	14	-	High Current	
P1.1	21	15	11	13	-	High Current	
P1.2	20	14	10	12	-	High Current	
P1.3	19	13	9	11	-	High Current	
P1.4	18	12	-	-	-	High Current	
P1.5	17	11	-	-	-	High Current	
P1.6	16	-	-	-	-	STD_IN OUT	
P2.0	1	35	25	1	15	STD_IN OUT/AN	



**General Device Information**
**Table 6 Package Pin Mapping (cont'd)**

Function	VQFN 40	TSSOP 38	TSSOP 28	VQFN 24	TSSOP 16	Pad Type	Notes
P2.1	2	36	26	2	-	STD_IN OUT/AN	
P2.2	3	37	27	3	-	STD_IN/ AN	
P2.3	4	38	-	-	-	STD_IN/ AN	
P2.4	5	1	-	-	-	STD_IN/ AN	
P2.5	6	2	28	-	-	STD_IN/ AN	
P2.6	7	3	1	4	16	STD_IN/ AN	
P2.7	8	4	2	5	1	STD_IN/ AN	
P2.8	9	5	3	5	1	STD_IN/ AN	
P2.9	10	6	4	6	2	STD_IN/ AN	
P2.10	11	7	5	7	3	STD_IN OUT/AN	
P2.11	12	8	6	8	4	STD_IN OUT/AN	
VSS	13	9	7	9	5	Power	Supply GND, ADC reference GND
VDD	14	10	8	10	6	Power	Supply VDD, ADC reference voltage/ ORC reference voltage
VDDP	15	10	8	10	6	Power	When VDD is supplied, VDDP has to be supplied with the same voltage.

**General Device Information**

**Table 6 Package Pin Mapping (cont'd)**

Function	VQFN 40	TSSOP 38	TSSOP 28	VQFN 24	TSSOP 16	Pad Type	Notes
VSSP	31	25	-	-	-	Power	I/O port ground
VDDP	32	26	-	-	-	Power	I/O port supply
VSSP	Exp. Pad	-	-	Exp. Pad	-	Power	<b>Exposed Die Pad</b> The exposed die pad is connected internally to VSSP. For proper operation, it is mandatory to connect the exposed pad to the board ground. For thermal aspects, please refer to the Package and Reliability chapter.

**2.2.2 Port I/O Function Description**

The following general building block is used to describe the I/O functions of each PORT pin:

**Table 7 Port I/O Function Description**

Function	Outputs		Inputs	
	ALT1	ALTn	Input	Input
P0.0		MODA.OUT	MODC.INA	
Pn.y	MODA.OUT		MODA.INA	MODC.INB